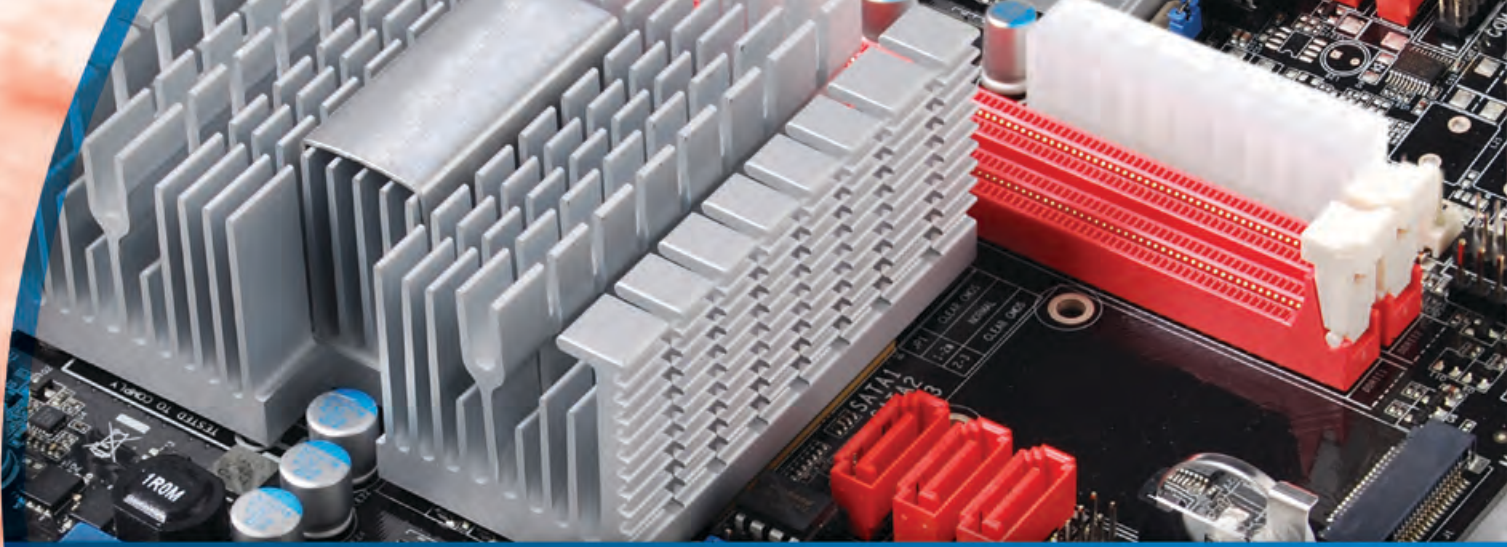


A close-up photograph of a red server heatsink mounted on a circuit board. The heatsink has multiple vertical fins. In the background, a fan is visible, and white lines represent cooling airflow directed towards the heatsink. The image is set against a warm, orange-toned background with a blue wave graphic on the right side.

CPU COOLER

SERVER HEATSINKS

 **Cooling Source[®]**



MISSION STATEMENT

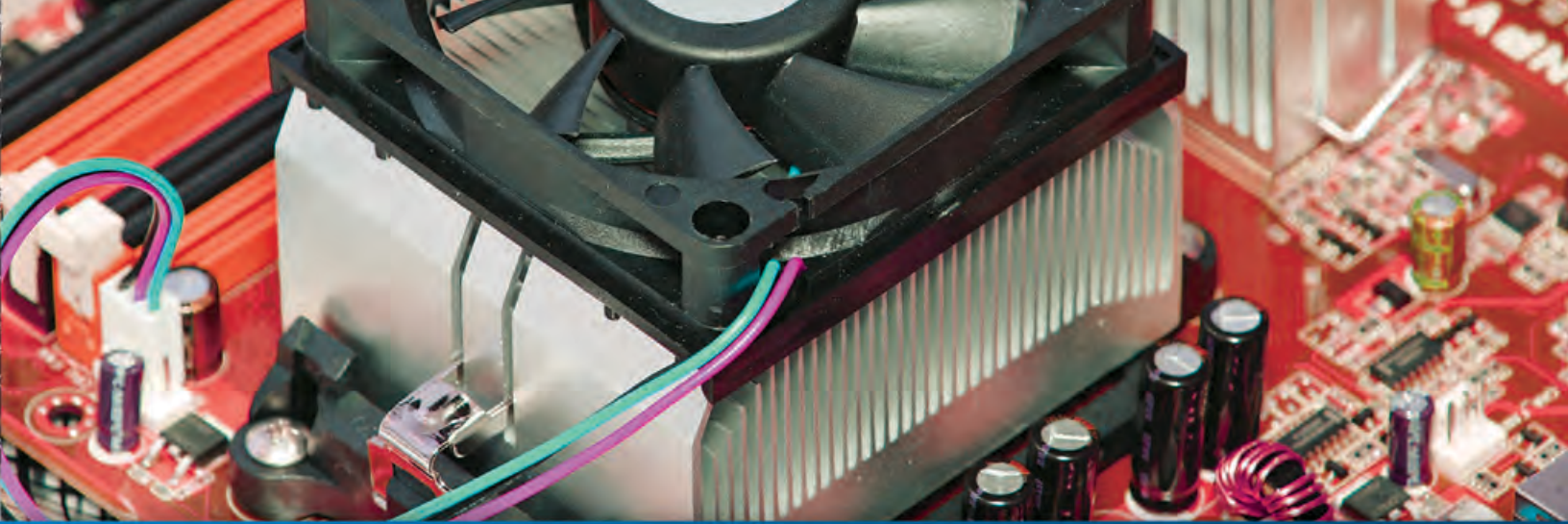
Cooling Source aims to deliver the highest value of services and products in a timely manner to our customers as the premier thermal solutions manufacturer, designer and service company.

COMPANY INTRODUCTION

Cooling Source, Inc. offers the most comprehensive value-added standard and custom heatsink solutions, including the latest technology to a wide range of markets. We provide design assistance and thermal analysis to help you achieve your goals. We will deliver the highest value to our customers as the premier manufacturer, designer and Service Company. Our ISO 9001-2008 and ISO14001 certified manufacturing plant is based in main land China to ensure you the lowest cost, best quality and supply chain continuity for your volume production.

 **Cooling Source**





COOLING SOURCE - THE DIFFERENCE

- Provide CFD modeling of heat sinks, boards and assemblies
- Mechanical design assistance on thermal solutions and attachments
- Broadest range of manufacturing processes
- Flexible fin shape designs
- Market leader in heat-pipe solutions
- Rapid prototyping for the validation of new projects
- Dedicated customer service and support
- Competitive global market cost
- Quality System: ISO 9001-2000 certified
- 100% inspection and testing of heat sink, heat-pipe and assembly
- Short lead times

DESIGN FLEXIBILITY

Cooling Source provides the broadest range of manufacturing processes to ensure you the most cost effective thermal solution.

- Die Casting
- Machining
- Extrusion – High aspect ratio
- Folded Fin
- Forging
- Skived Fin
- Swaged Fin
- Stamped Fin
- Heat-pipe Assembly
- Plastic injection molding
- Cold Plates
- CPU Coolers

1

COST EFFECTIVE MANUFACTURING

- Manufacture your volume requirements at our facility located in Shenzhen, China.
- RFQs, order placements and coordination performed by US-based personnel.
- Engineering and local customer service support.
- ISO 9001- 2000 certified manufacturing facility.
- High quality components with competitive, global market cost.
- Utilize suitable manufacturing processes to ensure lowest production cost.

2



ENGINEERING SUPPORT

- Provide thermal analysis of heat sinks, assemblies and boards for new designs using CFD modeling.
- Quick turn-around of prototypes and pre-production quantities to support short design cycles.
- Provide design proposal of heat sinks and thermal solution assemblies.

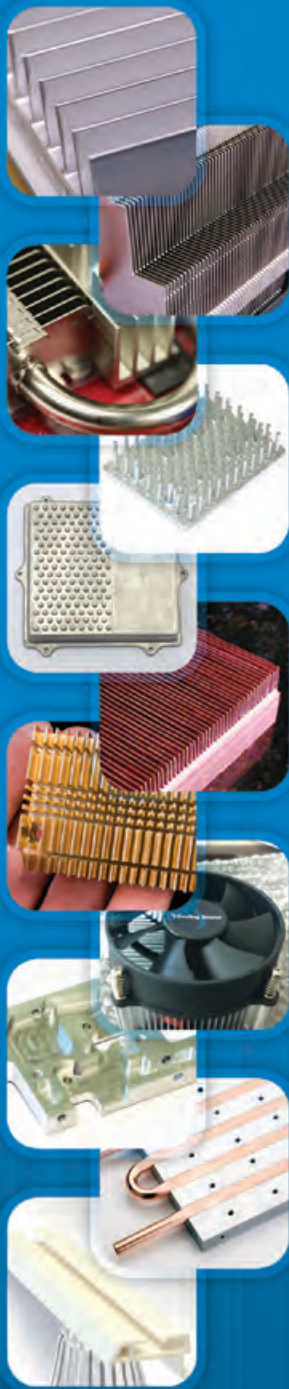
3

CSPN	CS804-116-0-1A	CS266-49-0-1A	CS266-50-0-1A	CS804-117-0-1A	CS266-51-0-1A	CS404-147-0-1A
						
PRODUCT SPECIFICATION						
Application area	1U Server thermal solution	1U Server thermal solution	2U and above 2U Server thermal solution	1U Server thermal solution	1U Server thermal solution	2U and above 2U Server thermal solution
Application for CPU socket	LGA 2011 (56 x 94 mm)	LGA 2011 (56 x 94 mm)	LGA 2011 (56 x 94 mm)	LGA 2011 (Square)	LGA 2011 (Square)	LGA 2011 (Square)
Application for CPU type	Intel® Sandy Bridge EP/EX Processors E5-2600 / E5-4600 (for Narrow ILM Mounting Only)	Intel® Sandy Bridge EP/EX Processors E5-2600 / E5-4600 (for Narrow ILM Mounting Only)	Intel® Sandy Bridge EP/EX Processors E5-2600 / E5-4600 (for Narrow ILM Mounting Only)	Intel® Xeon® E5-1600, E5-2600 & E5-4600 Series	Intel® Xeon® E5-1600, E5-2600 & E5-4600 Series	Intel® Xeon® E5-1600, E5-2600 & E5-4600 Series
Production technology	Copper Skiving	Copper Skiving plus DC fan.	Copper base plate and Aluminium fin with 5pcs φ6 "U" heatpipes plus DC Fan.	Copper Skiving	Copper Skiving plus DC fan	Copper base plate and Aluminium fin with 4pcs φ6 "U" heatpipes
Assembly method	Screw plus spring.	Screw plus spring.	Screw plus spring.	Screw plus spring.	Screw plus spring.	Screw plus spring.
Production dimension (mm)	106*72*24	106*78*28.5	104*81*65	88*88*24	89*92*28	95*90*66
Production weight (g)	504	494	418	448	406	743
Thermal interface material	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)
Back bracket	N/A	N/A	N/A	N/A	N/A	N/A
FAN SPECIFICATION						
Fan dimension (mm)	N/A	75*75*15	60*60*25	N/A	75*75*15	N/A
Rated voltage (V)	N/A	12	12	N/A	12	N/A
Bearing type	N/A	Two ball	Two ball	N/A	Two ball	N/A
Speed (RPM)	N/A	5000	7300	N/A	5000	N/A
Maximum air flow (CFM)	N/A	10,75	38,1	N/A	10,75	N/A
Acoustic (dBA)	N/A	55	47,2	N/A	55	N/A
Lifetime (H)	N/A	70,000	70,000	N/A	70,000	N/A
Fan line	N/A	4pins with PWM function	4pins with PWM function	N/A	4pins with PWM function	N/A

CSPN	CS266-52-0-1A	CS266-53-0-1A	CS804-118-0-1A	CS266-54-0-1A	CS266-55-0-1A	CS804-119-0-1A
						
PRODUCT SPECIFICATION						
Application area	2U and above 2U Server thermal solution.	3U and above 3U Server thermal solution.	1U Server thermal solution.	1U Server thermal solution.	2U and above 2U Server thermal solution.	1U Server thermal solution.
Application for CPU socket	LGA 2011 (Square)	LGA 2011 (Square)	LGA 1366 & 1356	LGA 1366 & 1356	LGA 1366 & 1356	LGA 775
Application for CPU type	Intel® Xeon® E5-1600, E5-2600 & E5-4600 Series	Intel® Xeon® E5-1600, E5-2600 & E5-4600 Series	Intel® Xeon™ X5500 Series and X5600 Series	Intel® Xeon™ X5500 Series and X5600 Series	Intel® Xeon™ X5500 Series and X5600 Series	Intel® Core 2 Quad, Core 2 Duo, Pentium®D Pentium® 4 & Xeon® 3000
Production technology	Copper base plate and Aluminium fin with 5pcs φ6 "U" heatpipes plus DC Fan.	Copper base plate and Aluminium fin with 5pcs φ6 "U" heatpipes plus DC Fan.	Copper Skiving	Copper Skiving plus DC fan.	Aluminium base plate and Aluminium fin with 3pcs φ6 "U" heatpipes plus DC Fan.	Copper Skiving
Assembly method	Screw plus spring.	Screw plus spring.	Screw plus spring.	Screw plus spring.	Screw plus spring.	Screw plus spring.
Production dimension (mm)	90*90*65	105.0*95.0*125.0	88.0*88.0*24.0	92*88*28	88.0*88.0*65.0	80*82*25.5
Production weight (g)	410	590	494	384	316	480
Thermal interface material	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)
Back bracket	N/A	N/A	Optional	Optional	Optional	Optional
FAN SPECIFICATION						
Fan dimension (mm)	60*60*25	92*92*25	N/A	75*75*15	60L*60W*25H	N/A
Rated voltage (V)	12	12	N/A	12V	12	N/A
Bearing type	Two ball	Two ball	N/A	Two ball	Two ball	N/A
Speed (RPM)	7300	4000	N/A	5000RPM	5000	N/A
Maximum air flow (CFM)	38,1	72,8	N/A	10.75CFM	40,4	N/A
Acoustic (dBA)	47,2	47	N/A	55dB	41	N/A
Lifetime (H)	70,000	70,000	N/A	70,000	70,000	N/A
Fan line	4pins with PWM function.	4pins with PWM function.	N/A	4pins with PWM function	4pins with PWM function	N/A

CSPN	CS266-56-0-1A	CS804-120-0-1A	CS266-57-0-1A	CS266-58-0-1A	CS266-59-0-1A	CS804-121-0-1A
						
PRODUCT SPECIFICATION						
Application area	1U Server thermal solution.	1U Server thermal solution.	1U Server thermal solution.	2U and above 2U Server thermal solution.	3U and above 3U Server thermal solution.	1U Server thermal solution.
Application for CPU socket	LGA 775	LGA 1155/1156/1150	LGA 1155/1156/1150	LGA 1155/1156/1150	LGA 1155/1156/1150	Pentium M, PGA 478/BGA 479
Application for CPU type	Intel® Core 2 Quad, Core 2 Duo, Pentium®D Pentium® 4 & Xeon® 3000	Intel® Core™ i7-2600, i5-2500 series Intel® Core™ i3 & i5, Xeon® Processor 3400 Series	Intel® Core™ i7-2600, i5-2500 series Intel® Core™ i3 & i5, Xeon® Processor 3400 Series	Intel® Core™ i7-2600, i5-2500 series Intel® Core™ i3 & i5, Xeon® Processor 3400 Series	Intel® Core™ i7-2600, i5-2500 series Intel® Core™ i3 & i5, Xeon® Processor 3400 Series	Intel® Atom®, Core® 2 Mobile, Pentium® M Processors Socket BGA479/PGA478
Production technology	Copper Skiving plus DC fan.	Copper Skiving	Copper Skiving plus DC fan.	Aluminium base plate and Aluminium fin with 3pcs φ6 "U" heatpipes plus DC fan.	Copper base plate and Aluminium fin with 5pcs φ6 "U" heatpipes plus DC fan.	Copper Skiving
Assembly method	Screw plus spring.	Screw plus spring.	Screw plus spring.	Screw plus spring.	Screw plus spring.	Screw plus spring.
Production dimension (mm)	80.5*85*29	88*88*24	89*92*28	88.0*89.0*65.0	105.0*95.0*125.0	50.0*50.0*20.0
Production weight (g)	384	454	396	318	596	156
Thermal interface material	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)
Back bracket	Optional	Optional	Optional	Optional	Optional	Optional
FAN SPECIFICATION						
Fan dimension (mm)	75*75*15	N/A	75*75*15	60*60*25	92*92*25	N/A
Rated voltage (V)	12V	N/A	12	12	12V	N/A
Bearing type	Two ball	N/A	Two ball	Two ball	Two ball	N/A
Speed (RPM)	5000RPM	N/A	5000RPM	5000	4000rpm	N/A
Maximum air flow (CFM)	10.75 CFM	N/A	10.75 CFM	40,4	72.8CFM	N/A
Acoustic (dBA)	55dBA	N/A	55dBA	41	47bBA	N/A
Lifetime (H)	70,000	N/A	70,000	70,000	70,000	N/A
Fan line	4pins with PWM function	N/A	4pins with PWM function	4pins with PWM function	4pins with PWM function	N/A

CSPN	CS505-172-F-1A	CS266-60-0-1A	CS804-122-0-1A	CS505-173-F-1A	CS266-61-F-1A
					
PRODUCT SPECIFICATION					
Application area	1U Server thermal solution.	1U Server thermal solution.	1U Server thermal solution.	1U Server thermal solution.	1U Server thermal solution.
Application for CPU socket	Pentium M, PGA 478/BGA 479	Pentium M, PGA 478/BGA 479	Socket G PGA988	Socket G PGA988	Socket G PGA988
Application for CPU type	Intel® Atom®, Core® 2 Mobile, Pentium® M Processors Socket BGA479/PGA478	Intel® Atom®, Core® 2 Mobile, Pentium® M Processors Socket BGA479/PGA478	For Intel® Core i7-600, i5-500, i5-400 & i3-300 Mobile Processor Series (Socket rPGA988A)	For Intel® Core i7-600, i5-500, i5-400 & i3-300 Mobile Processor Series (Socket rPGA988A)	For Intel® Core i7-600, i5-500, i5-400 & i3-300 Mobile Processor Series (Socket rPGA988A)
Production technology	Aluminium Extrusion	Copper Skiving plus DC fan.	Copper Skiving	Aluminium Extrusion	Copper Skiving plus DC fan.
Assembly method	Screw plus spring.	Screw plus spring.	Screw plus spring.	Screw plus spring.	Screw plus spring.
Production dimension (mm)	50.0*50.5*24.5	50.5*50.5*21	60.0*59.0*20.0	59.5*60*24	62*60*27
Production weight (g)	70	102	204	88	178
Thermal interface material	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)	AD66 (thermal conductivity>4.0)
Back bracket	Optional	Optional	Optional	Optional	Optional
FAN SPECIFICATION					
Fan dimension (mm)	N/A	40.5*40.5*10.5	N/A	N/A	50*50*10
Rated voltage (V)	N/A	12	N/A	N/A	12
Bearing type	N/A	Two Ball	N/A	N/A	Two Ball
Speed (RPM)	N/A	5000	N/A	N/A	4700
Maximum air flow (CFM)	N/A	7,21	N/A	N/A	11,93
Acoustic (dBA)	N/A	27	N/A	N/A	28,5
Lifetime (H)	N/A	70,000	N/A	N/A	70,000
Fan line	N/A	3pins	N/A	N/A	3 pins



- *Bonded Fin Heat sink*
- *Stamped Fin*
- *Heat-pipe Assembly*
- *Precision Forging*
- *Die Casting*
- *Skived Fin*
- *Extrusion*
- *Fansink*
- *Custom Machining*
- *Cold Plate*
- *Plastic Injection Molding*



3111 Independence Drive
Livermore, CA 94551

Call us now!
Tel: 925.292.1293
Fax: 925.292.5061

www.coolingsource.com